Inventor: Hsin-Hui Lee
Serial No.: 10/045,783 Filed: 01/12/2002
For: Method of Making a Wafer Level Chip Scale Package
Attorney Doc. No.: 67,200-591

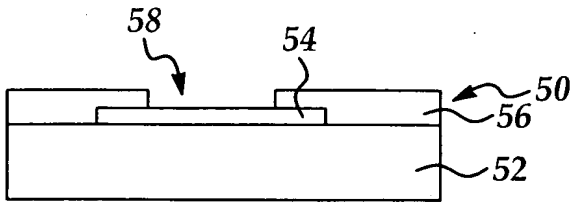

Figure 1A
Prior Art

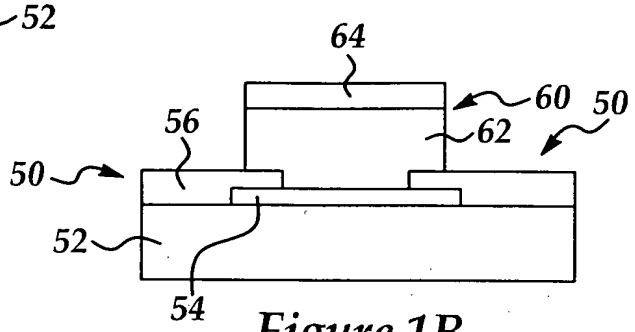

Figure 1B
Prior Art

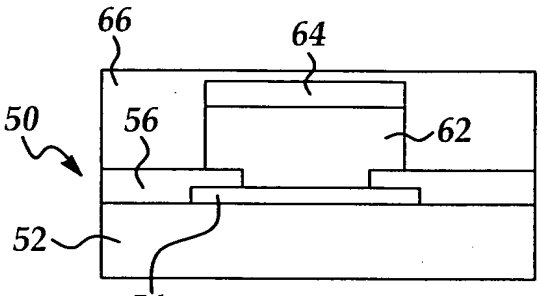

Figure 1C
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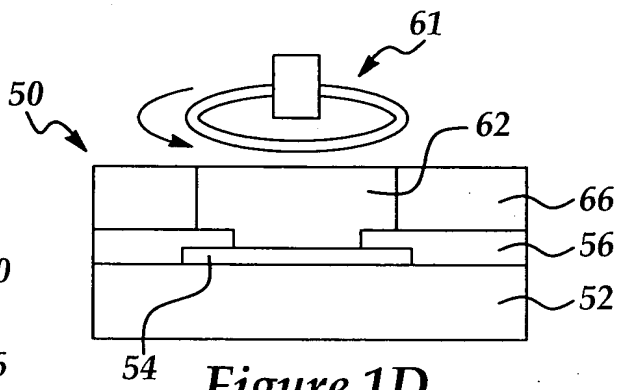

Figure 1D
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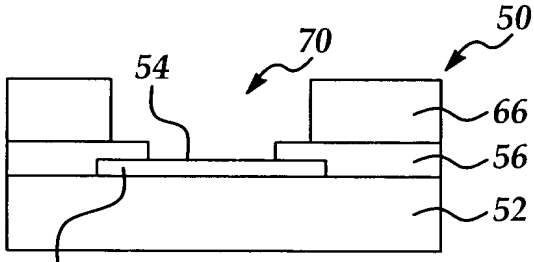

Figure 1E
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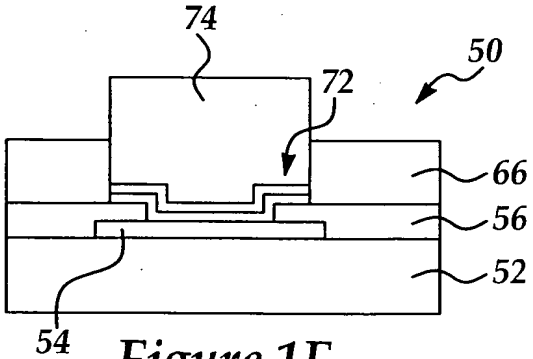

Figure 1F
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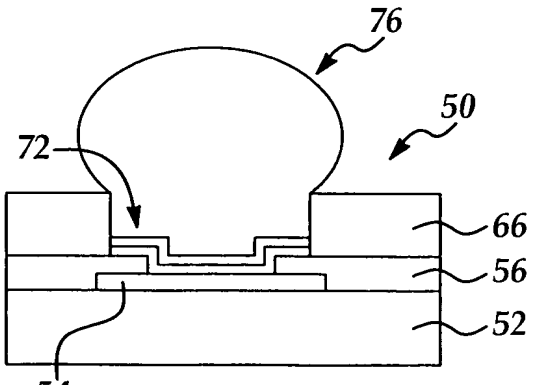

Figure 1G

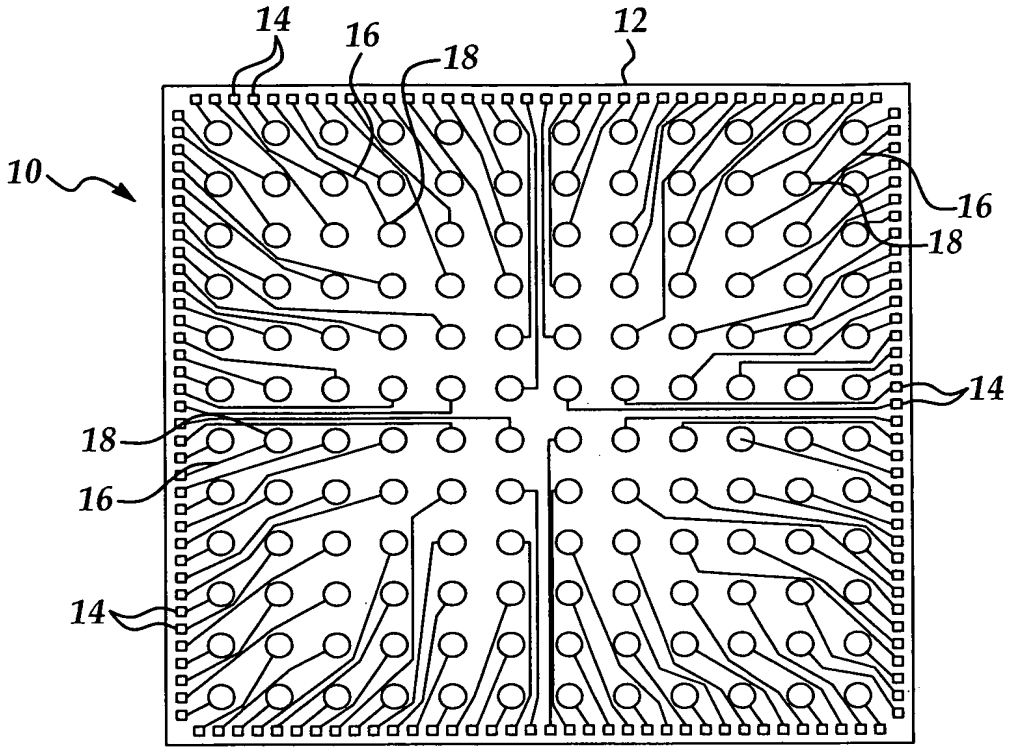

Figure 2
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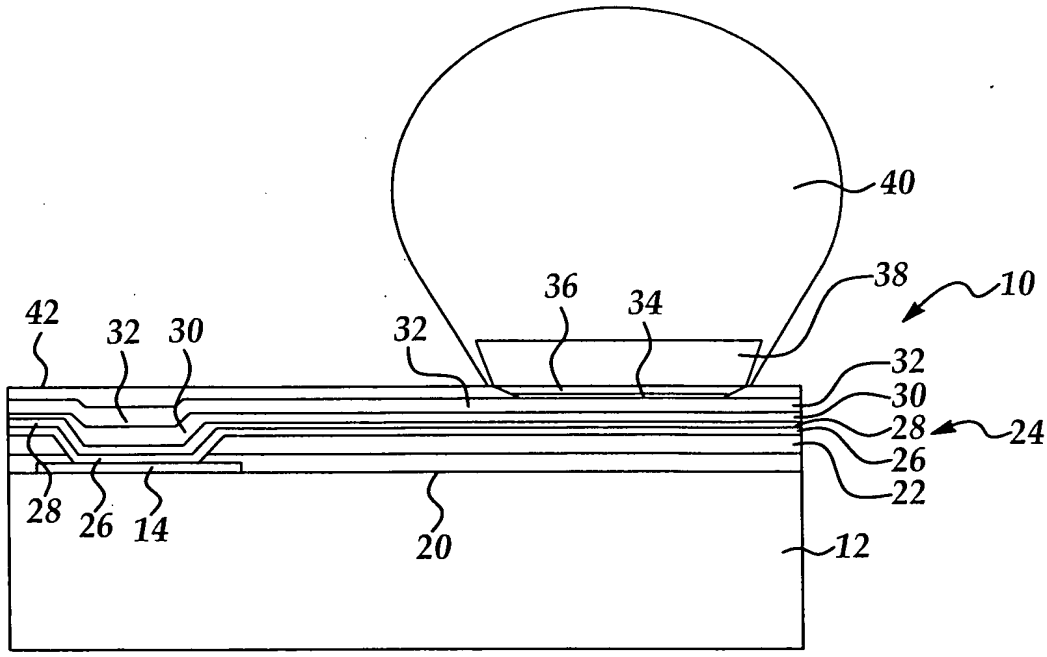


Figure 3
Prior Art

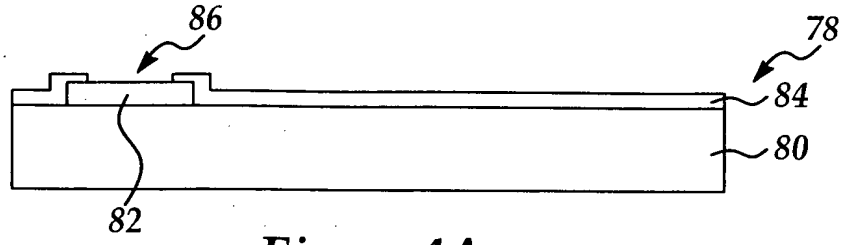


Figure 4A

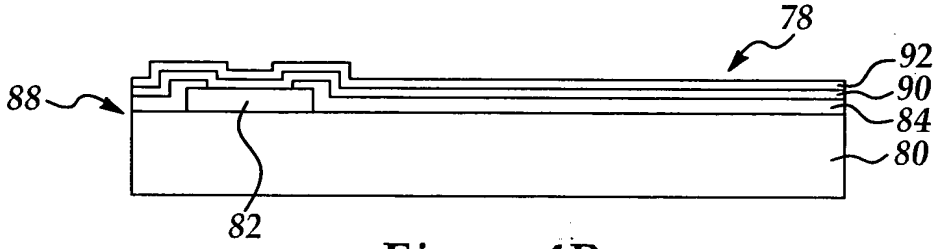
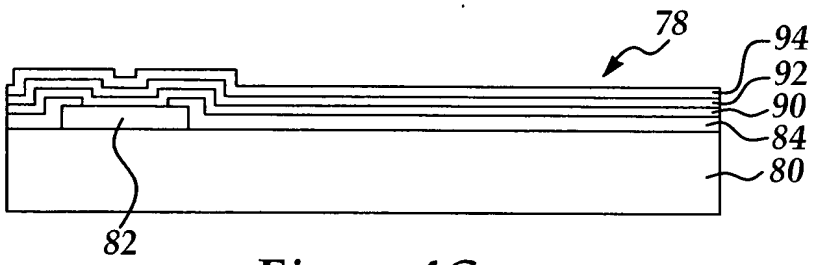


Figure 4B



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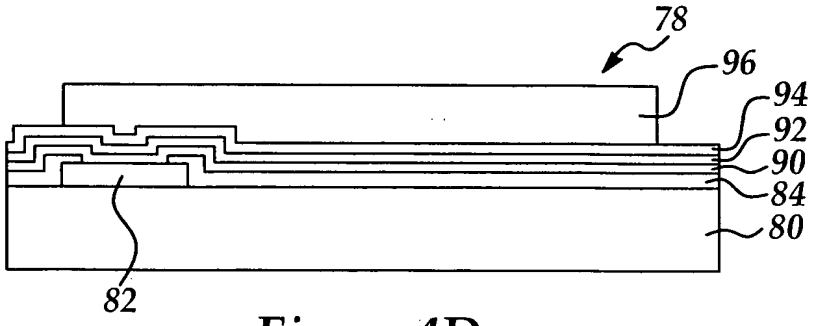

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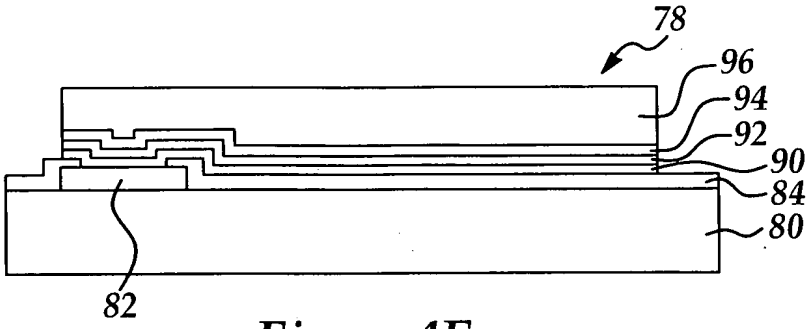

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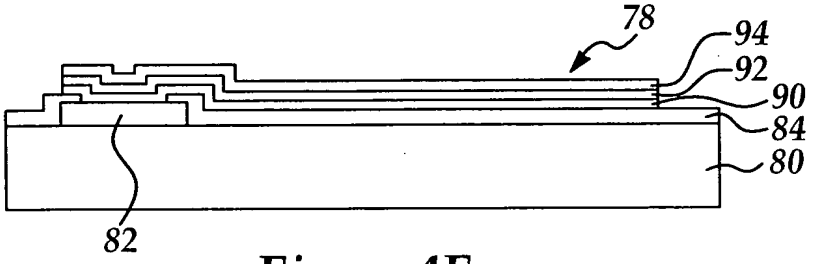

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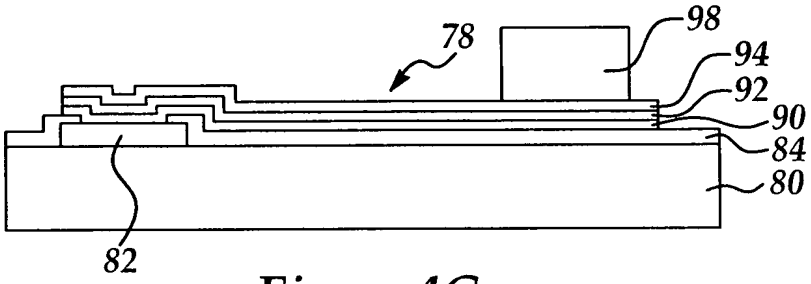

Figure 4G

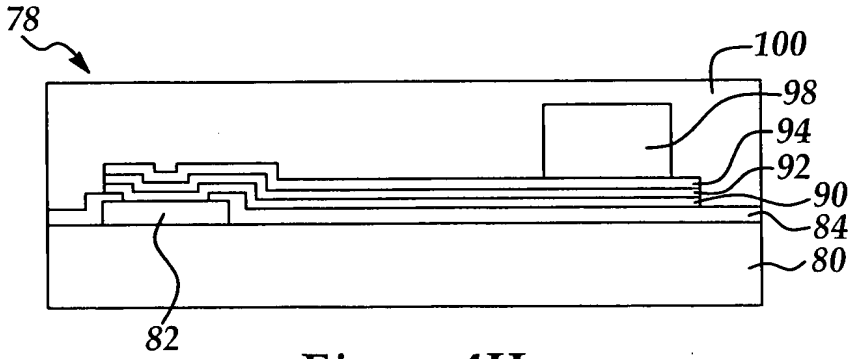

Figure 4H

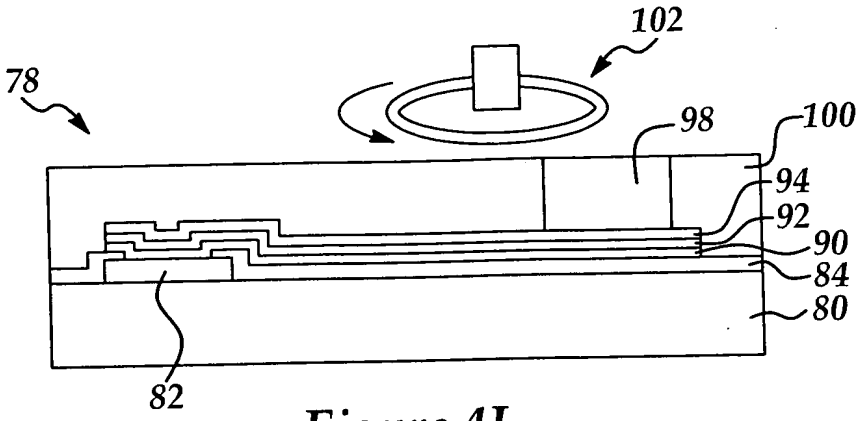

Figure 4I

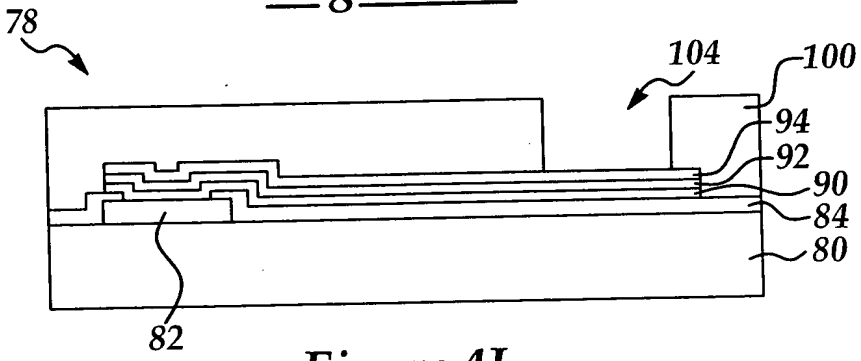

Figure 4J

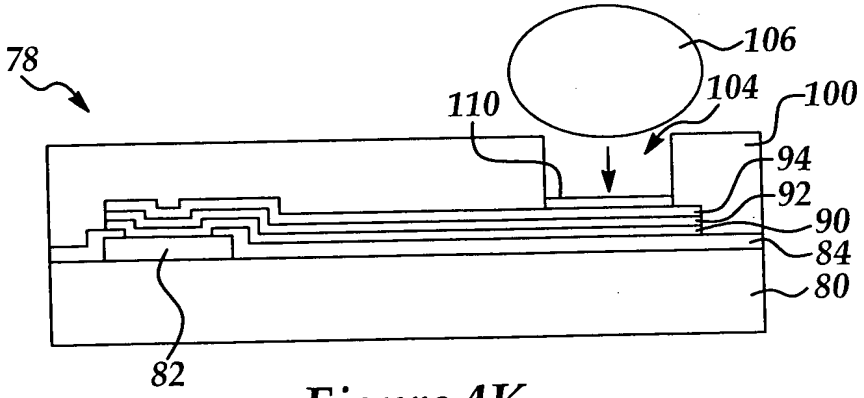

Figure 4K

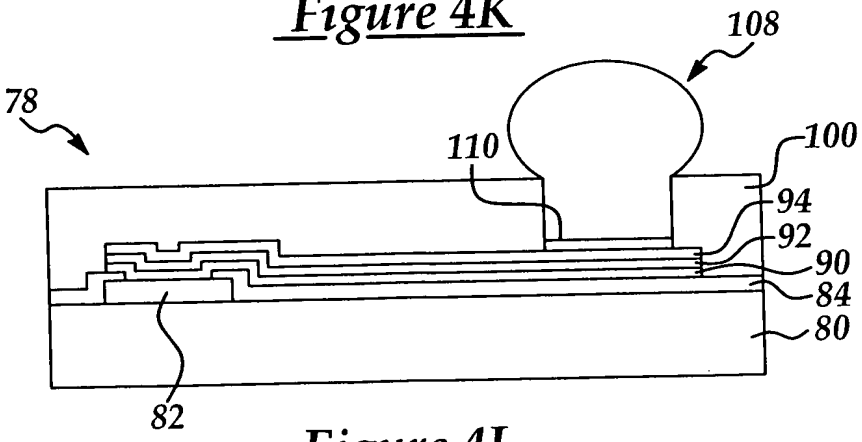

Figure 4L